

WHAT IS CLAIMED IS:

1. A digital micro-mirror device (DMD) packages, comprising:
a base substrate having a top surface and a bottom surface;
5 a metallic layer formed on the top surface of the base substrate;
a metallic adhesive formed on the metallic layer;
a semiconductor chip mounted on the metallic adhesive, the base substrate electrically
connected with the semiconductor chip;
one or more mirrors mounted on the semiconductor chip;
10 a hermetic sealing means covering the semiconductor chip including the one more
mirrors.

2. The DMD package of claim 1, which further comprises a heat sink attached on
the bottom surface of the base substrate.